

Title (en)

DLC HARD MATERIAL COATINGS ON BEARING MATERIALS CONTAINING COPPER

Title (de)

DLC HARTSTOFFBESCHICHTUNGEN AUF KUPFERHALTIGEN LAGERWERKSTOFFEN

Title (fr)

REVETEMENT EN UN MATERIAU DUR DLC SUR DES MATERIAUX A TENEUR EN CUIVRE POUR PALIERS

Publication

**EP 1769100 A1 20070404 (DE)**

Application

**EP 05731502 A 20050422**

Priority

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- CH 8972004 A 20040525

Abstract (en)

[origin: WO2005106065A1] Disclosed is a bearing material that is made of copper or a copper-containing alloy and is used in plain bearings comprising a coating which is deposited at least on some portions of the sliding surface and is composed at least of a supporting layer and a sliding layer. The sliding layer is embodied as a hard layer containing diamond-type carbon.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2005106065A1

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